

# Technical Data Sheet

## *FeedBond<sup>®</sup> EP-2015R*

### Non-Conductive Adhesive

#### Introduction:

*EP-2015R* is an epoxy type adhesive designed for die-attach applications, it can be applied for lead frame package. It has good adhesion on different substrates.

#### Characteristics:

- Excellent dispensability with minimal tailing and stringing
- Minimal bleeding and minimal volatiles

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Appearance	Red		
Viscosity @ 25°C	12000cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25°C	3.1	Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc @ 5rpm	FT-P008
Grind	< 25µm	Grind meter	FT-P026
Work Life @ 25°C	48 hours	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ -40°C	6 month	25% increase in visc. @ 5rpm	FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
Standard Cure Condition		60 minutes @ 150°C	

The tables shown above are typical values only. If you need to write a specification , please request our current Standard Release Specification.

**FeedBond® EP-2015R****Non-Conductive Die Attach Adhesive**

PHYSIOCHEMICAL PROPERTIES- POST CURE	TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature 127°C	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion Below Tg 49 ppm/°C Above Tg 182 ppm/°C	TMA Expansion Mode	FT-M016
Dynamic Tensile Modulus @ -60°C 3613MPa @ 25°C 2971 MPa @ 150°C 44MPa @ 250°C 34 MPa	Dynamic Mechanical Thermal  Analysis using <1.6 mm thick specimen	FT-M019
Weight loss <1.0% @300°C	TGA	FT-P010
Volume resistivity >10 <sup>13</sup> ohm-cm	megohmmeter	FT-P039
Thermal conductivity 0.2 W/mK	Hot Disk	FT-P022
MECHANICAL PROPERTIES- POST CURE	TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25°C >10kg/die @ 260°C >1kg/die	2mmx2mm Si die on Ag/Cu LF (80milx80 mil)	FT-M012

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**Instruction****Thawing**

Place the container to stand vertically for 30min ~90min. **DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

**Storage**

Adhesive should be stored @ -40°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

**Availability**

FeedBond adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.